

Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low R_{DS(ON)}

Product Summary

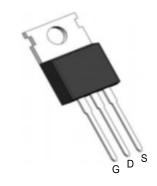


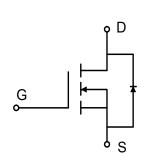
BVDSS	RDSON	ID
150V	9.5mΩ	120A

Applications

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

TO220AB Pin Configuration





Absolute Maximum Ratings (T_A = 25°C, unless otherwise noted)

Parameter	Symbol	Value	Unit		
Drain-Source Voltage		V _{DS}	150	V	
Gate-Source Voltage		V _{GS}	±20	V	
Continuous Desig Comment	T _C =25°C	1_	120	А	
Continuous Drain Current	T _C =100°C	ID	56		
Pulsed Drain Current ¹	Ідм	352	А		
Single Pulse Avalanche Energy ²		EAS	204.8	mJ	
Total Power Dissipation	T _C =25°C	P _D	178.6	W	
Operating Junction and Storage Temperature Range		ТЈ, Тѕтс	-55 to 150	°C	

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	ReJA	52	°C/W
Thermal Resistance from Junction-to-Case	R _{θJC}	0.7	°C/W



Electrical Characteristics (T_J = 25°C, unless otherwise noted)

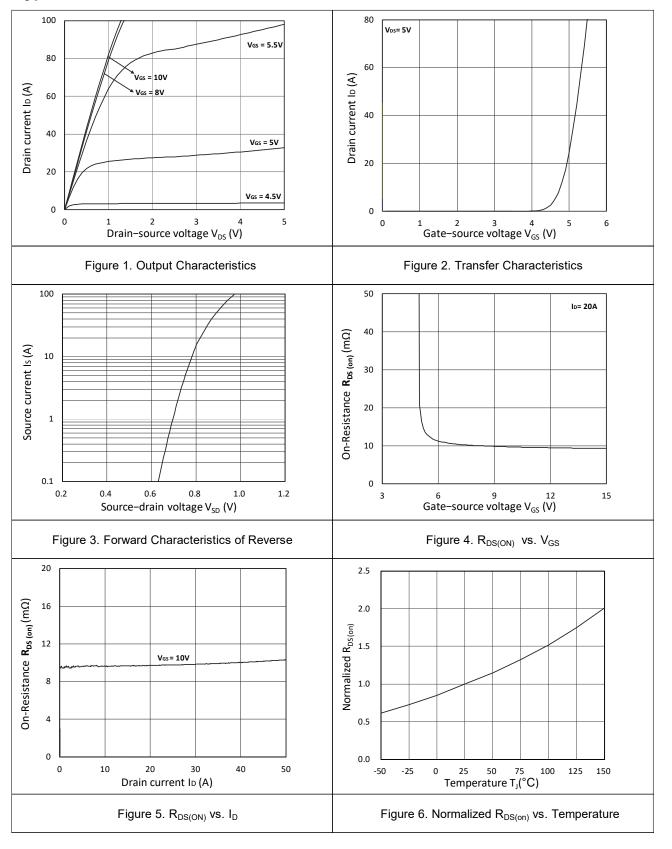
Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics		l		•			
Drain-Source Breakdown Voltage		V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	150	-	-	V
Gate-body Leakage Current		I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T _J =25°C	- I _{DSS}	V _{DS} = 150V, V _{GS} = 0V	-	-	1	μА
	T _J =100°C			-	-	100	
Gate-Threshold Voltage		V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2	3	4	V
Drain-Source On-Resistance ⁴		R _{DS(on)}	V _{GS} = 10V, I _D = 20A	-	9.5	11.5	mΩ
Forward Transconductance ⁴		g fs	V _{DS} = 10V, I _D = 20A	-	69	-	S
Dynamic Characteristic	s ⁵			1			
Input Capacitance		C _{iss}		-	3310	-	
Output Capacitance		Coss	V _{DS} = 75V, V _{GS} =0V, f =1MHz	-	268	-	pF
Reverse Transfer Capacitance		Crss		-	9.4	-	
Gate Resistance		Rg	f = 1MHz	-	3.2	-	Ω
Switching Characteristics ⁵							
Total Gate Charge		Qg	V _{GS} = 10V, V _{DS} = 75V, I _D = 20A	-	45	-	nC
Gate-Source Charge		Qgs		-	15	-	
Gate-Drain Charge		Q _{gd}		-	8.5	-	
Turn-On Delay Time		t _{d(on)}	$V_{GS} = 10V, V_{DD} = 75V,$ $R_{G} = 3\Omega, I_{D} = 20A$	-	16	-	ns
Rise Time Turn-Off Delay Time Fall Time		t _r		-	12	-	
		t _{d(off)}		-	30	-	
		t _f		-	18	-	
Body Diode Reverse Recovery Time		t _{rr}		-	76	-	ns
Body Diode Reverse Recovery Charge		Qrr	- I _F =20A, dl/dt=100A/μs	-	182	-	nC
Drain-Source Body Diode Characteristics							
Diode Forward Voltage ⁴		V _{SD}	I _S = 20A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current	T _C =25°C	Is	-	-	-	120	Α

Notes:

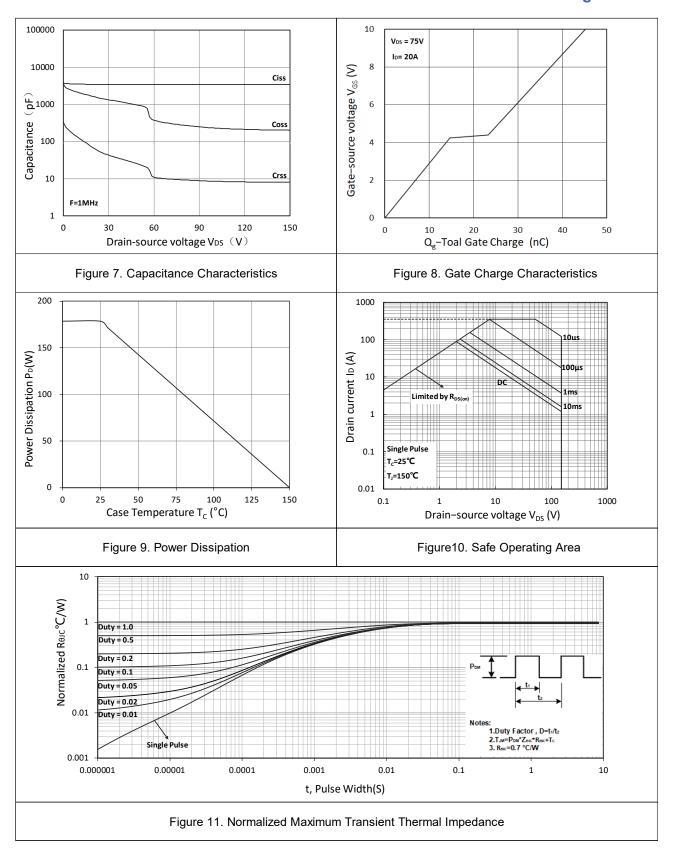
- 1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ =150°C
- 2. The EAS data shows Max. rating . The test condition is V_{DD} =50V, V_{GS} =10V,L=0.4mH, I_{AS} =32A.
- 3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- 4. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 5. This value is guaranteed by design hence it is not included in the production test.



Typical Characteristics







Test Circuit

N-Ch 150V Fast Switching MOSFETs

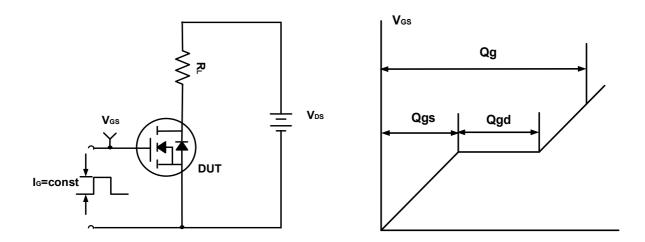


Figure A. Gate Charge Test Circuit & Waveforms

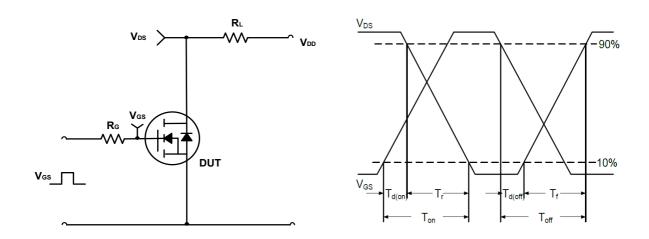


Figure B. Switching Test Circuit & Waveforms

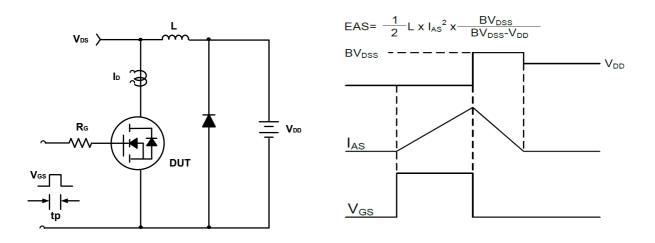
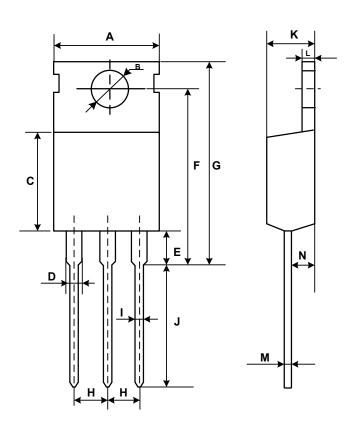


Figure C. Unclamped Inductive Switching Circuit & Waveforms



Mechanical Dimensions for TO-220



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SYMBOL	MM			
	MIN	MAX		
Α	9.70	10.30		
В	3.40	3.80		
С	8.80	9.40		
D	1.17	1.47		
E	2.60	3.50		
F	15.10	16.70		
G	19.55MAX			
Н	2.54REF			
1	0.70	0.95		
J	9.35	11.00		
K	4.30	4.77		
L	1.20	1.45		
М	0.40	0.65		
N	2.20	2.60		